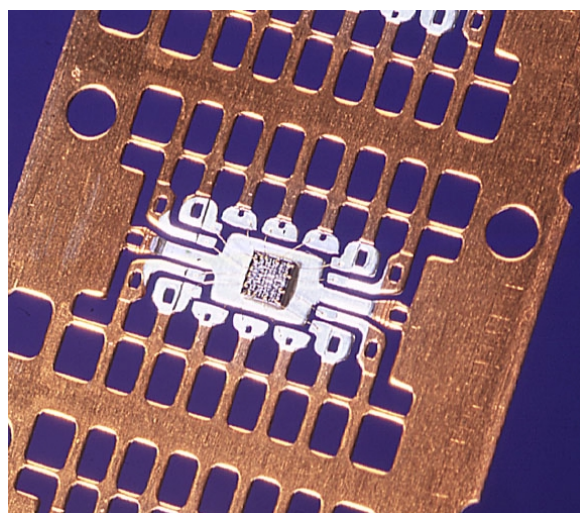




PACKAGE MATERIAL LIST

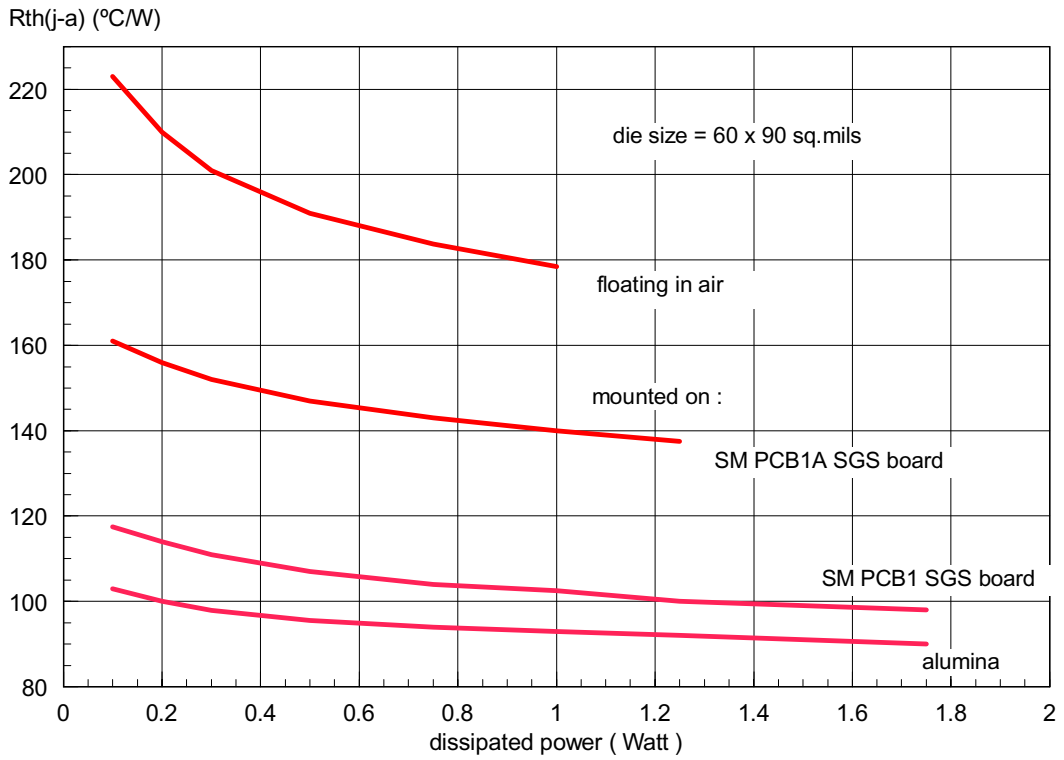
item #	material	thickness	thermal conductivity
leadframe	copper	0.20 mm	2.61 W/cm°C
die attach	epoxy glue (silver filler)	10-40 μm	0.01 W/cm°C
molding compound	epoxy resin	1.65 mm	0.0063W/cm°C



Charts enclosed :

- 1) $R_{th(j-a)}$ vs power dissipation
- 2) $Z_{th(j-a)}$ vs time width and die size

1)



2)

